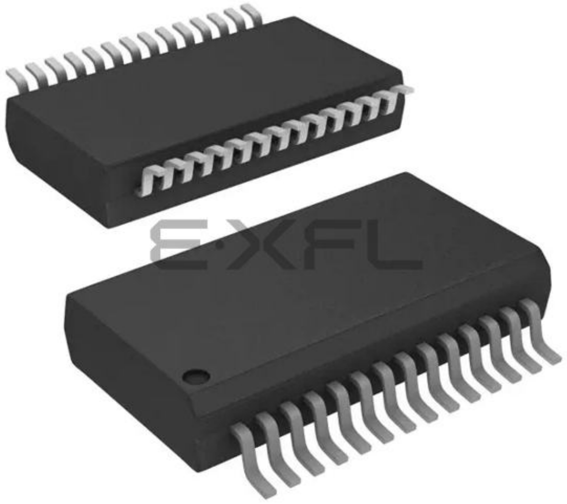
Microchip Technology - PIC16LC62BT-04/SS Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc62bt-04-ss

2.0 MEMORY ORGANIZATION

There are two memory blocks in each of these microcontrollers. Each block (Program Memory and Data Memory) has its own bus, so that concurrent access can occur.

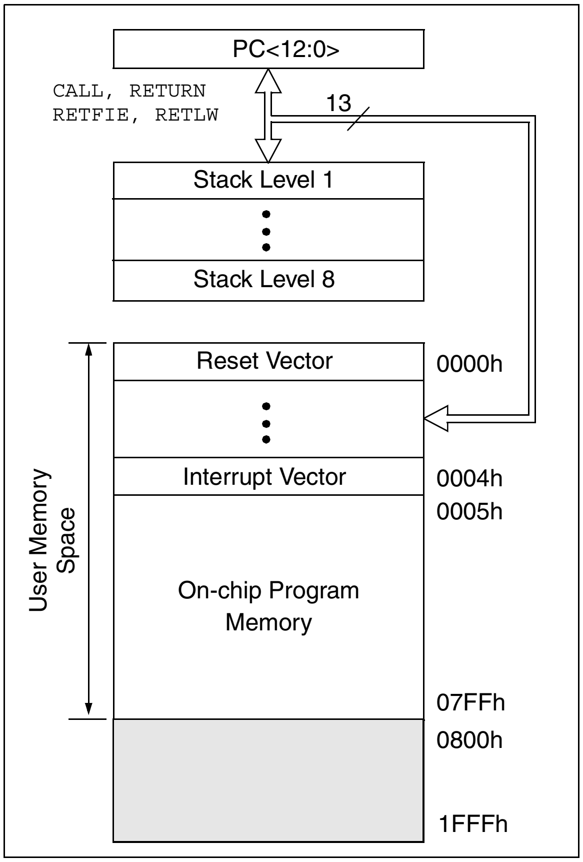
Additional information on device memory may be found in the PICmicro™ Mid-Range Reference Manual, (DS33023).

2.1 Program Memory Organization

The PIC16C62B/72A devices have a 13-bit program counter capable of addressing an 8K x 14 program memory space. Each device has 2K x 14 words of program memory. Accessing a location above 07FFh will cause a wraparound.

The reset vector is at 0000h and the interrupt vector is at 0004h.

FIGURE 2-1: PROGRAM MEMORY MAP AND STACK



2.2.2.4 PIE1 REGISTER

This register contains the individual enable bits for the peripheral interrupts.

Note:	Bit PEIE (INTCON<6>) must be set to enable any peripheral interrupt.

REGISTER 2-4: PIE1 REGISTER (ADDRESS 8Ch)

U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	ADIE[1]	—	—	SSPIE	CCP1IE	TMR2IE	TMR1IE
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n = Value at POR reset

bit 7: **Unimplemented:** Read as ‘0’

bit 6: **ADIE[1]**: A/D Converter Interrupt Enable bit
1 = Enables the A/D interrupt
0 = Disables the A/D interrupt

bit 5-4: **Unimplemented**: Read as ‘0’

bit 3: **SSPIE**: Synchronous Serial Port Interrupt Enable bit
1 = Enables the SSP interrupt
0 = Disables the SSP interrupt

bit 2: **CCP1IE**: CCP1 Interrupt Enable bit
1 = Enables the CCP1 interrupt
0 = Disables the CCP1 interrupt

bit 1: **TMR2IE**: TMR2 to PR2 Match Interrupt Enable bit
1 = Enables the TMR2 to PR2 match interrupt
0 = Disables the TMR2 to PR2 match interrupt

bit 0: **TMR1IE**: TMR1 Overflow Interrupt Enable bit
1 = Enables the TMR1 overflow interrupt
0 = Disables the TMR1 overflow interrupt

Note 1: The PIC16C62B does not have an A/D module. This bit location is reserved on these devices. Always maintain this bit clear.

2.3 PCL and PCLATH

The program counter (PC) specifies the address of the instruction to fetch for execution. The PC is 13 bits wide. The low byte is called the PCL register and is readable and writable. The high byte is called the PCH register. This register contains the PC<12:8> bits and is not directly accessible. All updates to the PCH register go through the PCLATH register.

2.3.1 STACK

The stack allows any combination of up to 8 program calls and interrupts to occur. The stack contains the return address from this branch in program execution.

Mid-range devices have an 8 level deep hardware stack. The stack space is not part of either program or data space and the stack pointer is not accessible. The PC is PUSHed onto the stack when a `CALL` instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a `RETURN, RETLW` or a `RETFIE` instruction execution. PCLATH is not modified when the stack is PUSHed or POPed.

After the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

2.4 Program Memory Paging

The `CALL` and `GOTO` instructions provide 11 bits of address to allow branching within any 2K program memory page. When doing a `CALL` or `GOTO` instruction, the upper bit of the address is provided by PCLATH<3>. The user must ensure that the page select bit is programmed to address the proper program memory page. If a return from a `CALL` instruction (or interrupt) is executed, the entire 13-bit PC is popped from the stack. Therefore, manipulation of the PCLATH<3> bit is not required for the return instructions.

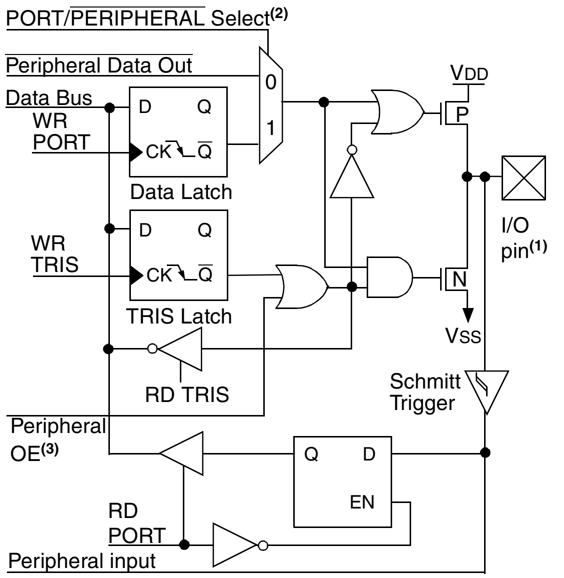
3.3 PORTC and the TRISC Register

PORTC is an 8-bit wide bi-directional port. The corresponding data direction register is TRISC. Setting a TRISC bit (=1) will make the corresponding PORTC pin an input, (i.e., put the corresponding output driver in a hi-impedance mode). Clearing a TRISC bit (=0) will make the corresponding PORTC pin an output, (i.e., put the contents of the output latch on the selected pin).

PORTC is multiplexed with several peripheral functions (Table 3-5). PORTC pins have Schmitt Trigger input buffers.

When enabling peripheral functions, care should be taken in defining TRIS bits for each PORTC pin. Some peripherals override the TRIS bit to make a pin an output, while other peripherals override the TRIS bit to make a pin an input. Since the TRIS bit override maybe in effect while the peripheral is enabled, read-modify-write instructions (`BSF, BCF, XORWF`) with TRISC as destination should be avoided. The user should refer to the corresponding peripheral section for the correct TRIS bit settings.

FIGURE 3-5: PORTC BLOCK DIAGRAM (PERIPHERAL OUTPUT OVERRIDE)



Note 1: I/O pins have diode protection to VDD and VSS.

2: Port/Peripheral select signal selects between port data and peripheral output.

3: Peripheral OE (output enable) is only activated if peripheral select is active.

TABLE 3-5 PORTC FUNCTIONS

Name	Bit#	Buffer Type	Function	TRISC Override
RC0/T1OSO/T1CKI	bit0	ST	Input/output port pin or Timer1 oscillator output/Timer1 clock input	Yes
RC1/T1OSI	bit1	ST	Input/output port pin or Timer1 oscillator input	Yes
RC2/CCP1	bit2	ST	Input/output port pin or Capture1 input/Compare1 output/PWM1 output	No
RC3/SCK/SCL	bit3	ST	RC3 can also be the synchronous serial clock for both SPI and I^2C modes.	No
RC4/SDI/SDA	bit4	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I^2C mode).	No
RC5/SDO	bit5	ST	Input/output port pin or Synchronous Serial Port data output	No
RC6	bit6	ST	Input/output port pin	No
RC7	bit7	ST	Input/output port pin	No

Legend: ST = Schmitt Trigger input

TABLE 3-6 SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
07h	PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	`xxxx xxxx`	`uuuu uuuu`
87h	TRISC	PORTC Data Direction Register								`1111 1111`	`1111 1111`

Legend: `x` = unknown, `u` = unchanged.

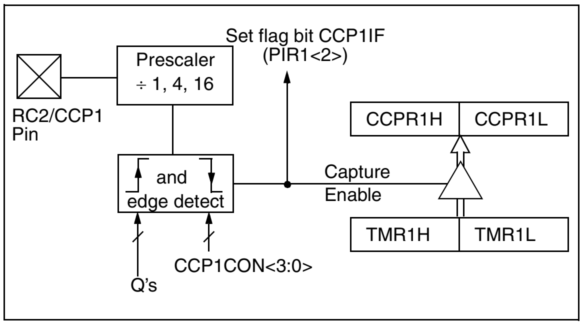
7.1 Capture Mode

In Capture mode, CCPR1H:CCPR1L captures the 16-bit value of the TMR1 register, when an event occurs on pin RC2/CCP1. An event is defined as:

- every falling edge
- every rising edge
- every 4th rising edge
- every 16th rising edge

An event is selected by control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). When a capture is made, the interrupt request flag bit ,CCP1IF (PIR1<2>), is set. It must be cleared in software. If another capture occurs before the value in register CCPR1 is read, the old captured value will be lost.

FIGURE 7-1: CAPTURE MODE OPERATION BLOCK DIAGRAM



7.1.1 CCP PIN CONFIGURATION

In Capture mode, the RC2/CCP1 pin should be configured as an input by setting the TRISC<2> bit.

Note:	If the RC2/CCP1 is configured as an output, a write to the port can cause a capture condition.

7.1.2 TIMER1 MODE SELECTION

Timer1 must be running in timer mode or synchronized counter mode for the CCP module to use the capture feature. In asynchronous counter mode, the capture operation may not work consistently.

7.1.3 SOFTWARE INTERRUPT

When the Capture mode is changed, a false capture interrupt may be generated. The user should clear CCP1IE (PIE1<2>) before changing the capture mode to avoid false interrupts. Clear the interrupt flag bit, CCP1IE before setting CCP1IE.

7.1.4 CCP PRESCALER

There are four prescaler settings, specified by bits CCP1M3:CCP1M0. Whenever the CCP module is turned off, or the CCP module is not in capture mode, the prescaler counter is cleared. This means that any reset will clear the prescaler counter.

Switching from one capture prescaler to another may generate an interrupt. Also, the prescaler counter will not be cleared, therefore the first capture may be from a non-zero prescaler. Example 7-1 shows the recommended method for switching between capture prescalers. This example also clears the prescaler counter and will not generate the “false” interrupt.

EXAMPLE 7-1: CHANGING BETWEEN CAPTURE PRESCALERS

```
CLRF   CCP1CON      ;Turn CCP module off
MOVLW  NEW_CAPT_PS  ;Load the W reg with
                    ; the new prescaler
                    ; mode value and CCP ON
MOVWF  CCP1CON      ;Load CCP1CON with this
                    ; value
```

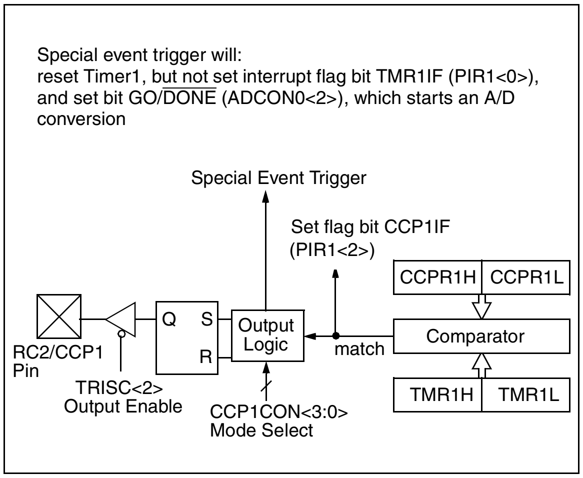
7.2 Compare Mode

In Compare mode, the 16-bit CCPR1 register value is constantly compared against the TMR1 register pair value. When a match occurs, the RC2/CCP1 pin is:

- driven High
- driven Low
- remains Unchanged

The action on the pin is based on the value of control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). The interrupt flag bit, CCP1IF, is set on all compare matches.

FIGURE 7-2: COMPARE MODE OPERATION BLOCK DIAGRAM



7.2.1 CCP PIN CONFIGURATION

The user must configure the RC2/CCP1 pin as an output by clearing the TRISC<2> bit.

Note:	Clearing the CCP1CON register will force the RC2/CCP1 compare output latch to the default low level. This is not the data latch.

7.2.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode if the CCP module is using the compare feature. In Asynchronous Counter mode, the compare operation may not work.

7.2.3 SOFTWARE INTERRUPT MODE

When a generated software interrupt is chosen, the CCP1 pin is not affected. Only a CCP interrupt is generated (if enabled).

7.2.4 SPECIAL EVENT TRIGGER

In this mode, an internal hardware trigger is generated, which may be used to initiate an action.

The special event trigger output of CCP1 resets the TMR1 register pair. This allows the CCPR1 register to effectively be a 16-bit programmable period register for Timer1.

The special trigger output of CCP1 resets the TMR1 register pair and starts an A/D conversion (if the A/D module is enabled).

TABLE 7-3 REGISTERS ASSOCIATED WITH CAPTURE, COMPARE, AND TIMER1

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other resets
0Bh,8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	`0000 000x`	`0000 000u`
0Ch	PIR1	—	ADIF	—	—	SSPIF	CCP1IF	TMR2IF	TMR1IF	`-0-- 0000`	`-0-- 0000`
8Ch	PIE1	—	ADIE	—	—	SSPIE	CCP1IE	TMR2IE	TMR1IE	`-0-- 0000`	`-0-- 0000`
87h	TRISC	PORTC Data Direction Register								`1111 1111`	`1111 1111`
0Eh	TMR1L	Holding register for the Least Significant Byte of the 16-bit TMR1 register								`xxxx xxxx`	`uuuu uuuu`
0Fh	TMR1H	Holding register for the Most Significant Byte of the 16-bit TMR1register								`xxxx xxxx`	`uuuu uuuu`
10h	T1CON	—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	`--00 0000`	`--uu uuuu`
15h	CCPR1L	Capture/Compare/PWM register1 (LSB)								`xxxx xxxx`	`uuuu uuuu`
16h	CCPR1H	Capture/Compare/PWM register1 (MSB)								`xxxx xxxx`	`uuuu uuuu`
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	`--00 0000`	`--00 0000`

Legend: `x` = unknown, `u` = unchanged, `-` = unimplemented read as '0'. Shaded cells are not used by Capture and Timer1.

8.0 SYNCHRONOUS SERIAL PORT (SSP) MODULE

8.1 SSP Module Overview

The Synchronous Serial Port (SSP) module is a serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be Serial EEPROMs, shift registers, display drivers, A/D converters, etc. The SSP module can operate in one of two modes:

- Serial Peripheral Interface (SPI)
- Inter-Integrated Circuit (I^2C)

For more information on SSP operation (including an I^2C Overview), refer to the PIC® MCU Mid-Range Reference Manual, (DS33023). Also, refer to Application Note AN578, *"Use of the SSP Module in the I^2C Multi-Master Environment."*

8.2 SPI Mode

This section contains register definitions and operational characteristics of the SPI module.

Additional information on SPI operation may be found in the PIC® MCU Mid-Range Reference Manual, (DS33023).

8.2.1 OPERATION OF SSP MODULE IN SPI MODE

A block diagram of the SSP Module in SPI Mode is shown in Figure 8-1.

The SPI mode allows 8-bits of data to be synchronously transmitted and received simultaneously. To accomplish communication, three pins are used:

- Serial Data Out (SDO)RC5/SDO
- Serial Data In (SDI)RC4/SDI/SDA
- Serial Clock (SCK)RC3/SCK/SCL

Additionally, a fourth pin may be used when in a slave mode of operation:

- Slave Select ($\overline{\text{SS}}$)RA5/$\overline{\text{SS}}$/AN4

When initializing the SPI, several options need to be specified. This is done by programming the appropriate control bits in the SSPCON register (SSPCON<5:0>) and SSPSTAT<7:6>. These control bits allow the following to be specified:

- Master Operation (SCK is the clock output)
- Slave Mode (SCK is the clock input)
- Clock Polarity (Idle state of SCK)
- Clock Edge (Output data on rising/falling edge of SCK)
- Clock Rate (master operation only)
- Slave Select Mode (Slave mode only)

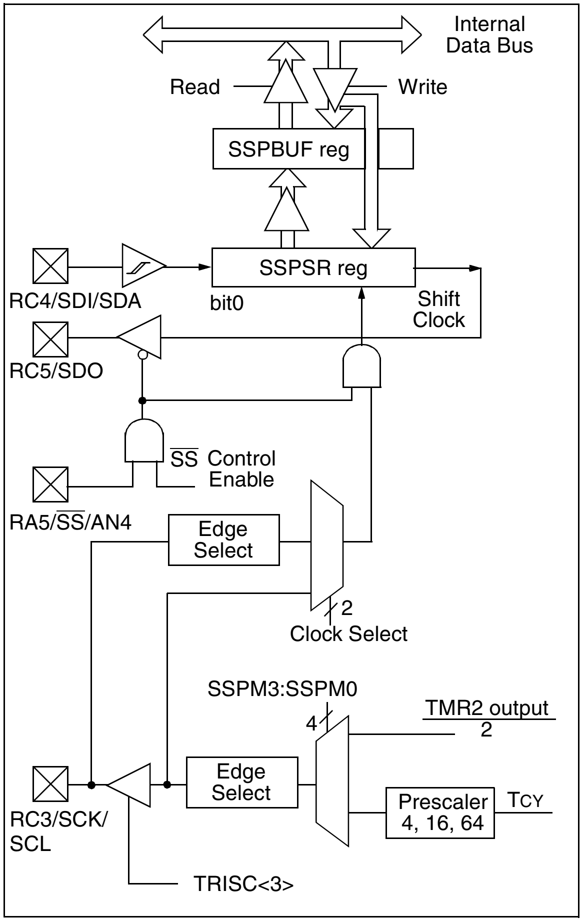
To enable the serial port, SSP Enable bit, SSPEN (SSPCON<5>) must be set. To reset or reconfigure SPI mode, clear bit SSPEN, re-initialize the SSPCON register, and then set bit SSPEN. This configures the SDI, SDO, SCK and $\overline{\text{SS}}$ pins as serial port pins. For the pins to behave as the serial port function, they must have their data direction bits (in the TRISC register) appropriately programmed. That is:

- SDI must have TRISC<4> set
- SDO must have TRISC<5> cleared
- SCK (master operation) must have TRISC<3> cleared
- SCK (Slave mode) must have TRISC<3> set
- $\overline{\text{SS}}$ must have TRISA<5> set (if used)

Note: When the SPI is in Slave Mode with $\overline{\text{SS}}$ pin control enabled, (SSPCON<3:0> = `0100`) the SPI module will reset if the $\overline{\text{SS}}$ pin is set to VDD.

Note: If the SPI is used in Slave Mode with CKE = '1', then the $\overline{\text{SS}}$ pin control must be enabled.

FIGURE 8-1: SSP BLOCK DIAGRAM (SPI MODE)



When the A/D conversion is complete, the result is loaded into the ADRES register, the GO/$\overline{\text{DONE}}$ bit, ADCON0<2>, is cleared, and the A/D interrupt flag bit, ADIF, is set. The block diagram of the A/D module is shown in Figure 9-1.

The value that is in the ADRES register is not modified for a Power-on Reset. The ADRES register will contain unknown data after a Power-on Reset.

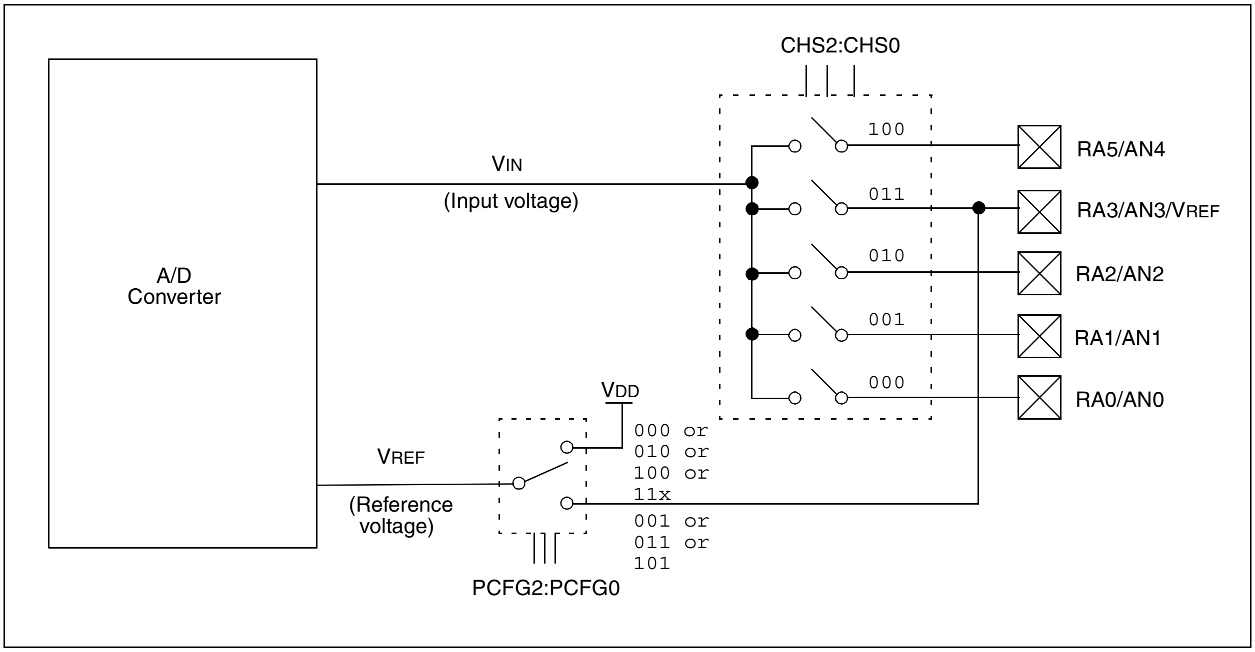
After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as an input. To determine acquisition time, see Section 9.1. After this acquisition time has elapsed, the A/D conversion can be started. The following steps should be followed for doing an A/D conversion:

1. Configure the A/D module:
   - Configure analog pins / voltage reference / and digital I/O (ADCON1)
   - Select A/D input channel (ADCON0)
   - Select A/D conversion clock (ADCON0)
   - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if desired):
   - Clear ADIF bit
   - Set ADIE bit
   - Set GIE bit
3. Wait the required acquisition time.
4. Start conversion:
   - Set GO/$\overline{\text{DONE}}$ bit (ADCON0)
5. Wait for A/D conversion to complete, by either:
   - Polling for the GO/$\overline{\text{DONE}}$ bit to be cleared

   OR

   - Waiting for the A/D interrupt
6. Read A/D Result register (ADRES), clear bit ADIF if required.
7. For next conversion, go to step 1 or step 2 as required. The A/D conversion time per bit is defined as T_{AD}. A minimum wait of $2T_{AD}$ is required before next acquisition starts.

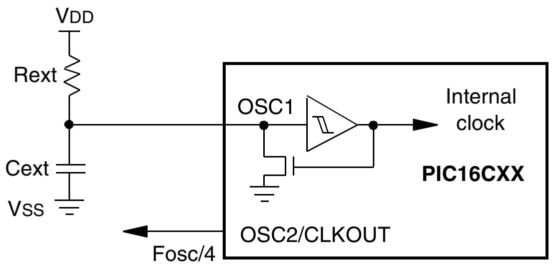
FIGURE 9-1: A/D BLOCK DIAGRAM



10.2.3 RC OSCILLATOR

For timing insensitive applications, the “RC” device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (REXT) and capacitor (CEXT) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low CEXT values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 10-4 shows how the R/C combination is connected to the PIC16CXXX.

FIGURE 10-4: RC OSCILLATOR MODE



Recommended values: 3 kΩ ≤ Rext ≤ 100 kΩ
Cext > 20pF

10.3 Reset

The PIC16CXXX differentiates between various kinds of reset:

- Power-on Reset (POR)
- $\overline{\text{MCLR}}$ reset during normal operation
- $\overline{\text{MCLR}}$ reset during SLEEP
- WDT Reset (during normal operation)
- WDT Wake-up (during SLEEP)
- Brown-out Reset (BOR)

Some registers are not affected in any reset condition; their status is unknown on POR and unchanged by any other reset. Most other registers are reset to a “reset state” on Power-on Reset (POR), on the $\overline{\text{MCLR}}$ and WDT Reset, on $\overline{\text{MCLR}}$ reset during SLEEP, and on Brown-out Reset (BOR). They are not affected by a WDT Wake-up from SLEEP, which is viewed as the resumption of normal operation. The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are set or cleared depending on the reset situation, as indicated in Table 10-4. These bits are used in software to determine the nature of the reset. See Table 10-6 for a full description of reset states of all registers.

A simplified block diagram of the on-chip reset circuit is shown in Figure 10-5.

The PIC devices have a $\overline{\text{MCLR}}$ noise filter in the $\overline{\text{MCLR}}$ reset path. The filter will ignore small pulses. However, a valid $\overline{\text{MCLR}}$ pulse must meet the minimum pulse width (TmcL, Specification #30).

No internal reset source (WDT, BOR, POR) willdrive the $\overline{\text{MCLR}}$ pin low.

IORLW	**Inclusive OR Literal with W**
Syntax:	[*label*] IORLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) .OR. k → (W)
Status Affected:	Z
Description:	The contents of the W register is OR’ed with the eight bit literal 'k'. The result is placed in the W register.

IORWF	**Inclusive OR W with f**
Syntax:	[*label*] IORWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) .OR. (f) → (destination)
Status Affected:	Z
Description:	Inclusive OR the W register with register 'f'. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.

MOVF	**Move f**
Syntax:	[*label*] MOVF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(f) → (destination)
Status Affected:	Z
Description:	The contents of register f is moved to a destination dependant upon the status of d. If d = 0, destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register since status flag Z is affected.

MOVLW	**Move Literal to W**
Syntax:	[*label*] MOVLW k
Operands:	0 ≤ k ≤ 255
Operation:	k → (W)
Status Affected:	None
Description:	The eight bit literal 'k' is loaded into W register. The don’t cares will assemble as 0’s.

MOVWF	**Move W to f**
Syntax:	[*label*] MOVWF f
Operands:	0 ≤ f ≤ 127
Operation:	(W) → (f)
Status Affected:	None
Description:	Move data from W register to register 'f'.

NOP	**No Operation**
Syntax:	[*label*] NOP
Operands:	None
Operation:	No operation
Status Affected:	None
Description:	No operation.

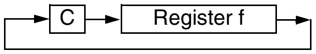
RETFIE	**Return from Interrupt**
Syntax:	[*label*] RETFIE
Operands:	None
Operation:	TOS → PC, 1 → GIE
Status Affected:	None

RETLW	**Return with Literal in W**
Syntax:	[*label*] RETLW k
Operands:	$0 \le k \le 255$
Operation:	k → (W); TOS → PC
Status Affected:	None
Description:	The W register is loaded with the eight bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two cycle instruction.

RETURN	**Return from Subroutine**
Syntax:	[*label*] RETURN
Operands:	None
Operation:	TOS → PC
Status Affected:	None
Description:	Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a two cycle instruction.

RLF	**Rotate Left f through Carry**
Syntax:	[*label*] RLF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	See description below
Status Affected:	C
Description:	The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is stored back in register 'f'.

RRF	**Rotate Right f through Carry**
Syntax:	[*label*] RRF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	See description below
Status Affected:	C
Description:	The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.



SLEEP	
Syntax:	[*label*] SLEEP
Operands:	None
Operation:	00h → WDT, 0 → WDT prescaler, 1 → $\overline{\text{TO}}$, 0 → $\overline{\text{PD}}$
Status Affected:	$\overline{\text{TO}}$, $\overline{\text{PD}}$
Description:	The power-down status bit, $\overline{\text{PD}}$ is cleared. Time-out status bit, $\overline{\text{TO}}$ is set. Watchdog Timer and its prescaler are cleared. The processor is put into SLEEP mode with the oscillator stopped. See Section 10.13 for more details.

13.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (†)

Ambient temperature under bias	-55°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD}, $\overline{\text{MCLR}}$, and RA4)	-0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS}	-0.3V to +7.5V
Voltage on $\overline{\text{MCLR}}$ with respect to V_{SS} (Note 2)	0V to +13.25V
Voltage on RA4 with respect to Vss	0V to +8.5V
Total power dissipation (Note 1)	1.0W
Maximum current out of V_{SS} pin	300 mA
Maximum current into V_{DD} pin	250 mA
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	±20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA and PORTB (combined)	200 mA
Maximum current sourced by PORTA and PORTB (combined)	200 mA
Maximum current sunk by PORTC	200 mA
Maximum current sourced by PORTC	200 mA

Note 1: Power dissipation is calculated as follows: $Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{Ol} \times I_{OL})$

2: Voltage spikes below V_{SS} at the $\overline{\text{MCLR}}/V_{PP}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the $\overline{\text{MCLR}}/V_{PP}$ pin, rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

13.1 DC Characteristics: PIC16C62B/72A-04 (Commercial, Industrial, Extended) PIC16C62B/72A-20 (Commercial, Industrial, Extended)

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤+125°C for extended					
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001 D001A	VDD	Supply Voltage	4.0 4.5 VBOR*	- - -	5.5 5.5 5.5	V V V	XT, RC and LP osc mode HS osc mode BOR enabled (Note 7)
D002*	VDR	RAM Data Retention **Voltage** (Note 1)	-	1.5	-	V	
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	-	VSS	-	V	See section on Power-on Reset for details
D004* D004A*	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05 TBD	- -	- -	V/ms	PWRT enabled ($\overline{\text{PWRTE}}$ bit clear) PWRT disabled ($\overline{\text{PWRTE}}$ bit set) See section on Power-on Reset for details
D005	VBOR	Brown-out Reset voltage trip point	3.65	-	4.35	V	BODEN bit set
D010	IDD	**Supply Current** (Note 2, 5)	-	2.7	5	mA	XT, RC osc modes FOSC = 4 MHz, VDD = 5.5V (Note 4)
D013			-	10	20	mA	HS osc mode FOSC = 20 MHz, VDD = 5.5V
D020	IPD	**Power-down Current** (Note 3, 5)	-	10.5	42	µA	VDD = 4.0V, WDT enabled,-40°C to +85°C
			-	1.5	16	µA	VDD = 4.0V, WDT disabled, 0°C to +70°C
D021			-	1.5	19	µA	VDD = 4.0V, WDT disabled,-40°C to +85°C
D021B			-	2.5	19	µA	VDD = 4.0V, WDT disabled,-40°C to +125°C
		Module Differential Current (Note 6)					
D022*	ΔIWDT	Watchdog Timer	-	6.0	20	µA	WDTE BIT SET, VDD = 4.0V
D022A*	ΔIBOR	Brown-out Reset	-	TBD	200	µA	BODEN bit set, VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc mode, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

7: This is the voltage where the device enters the Brown-out Reset. When BOR is enabled, the device will perform a brown-out reset when VDD falls below VBOR.

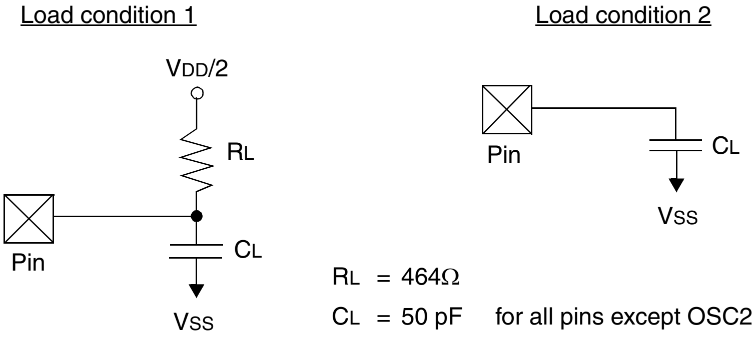
13.4.2 TIMING CONDITIONS

The temperature and voltages specified in Table 13-1 apply to all timing specifications unless otherwise noted. Figure 13-4 specifies the load conditions for the timing specifications.

TABLE 13-1: TEMPERATURE AND VOLTAGE SPECIFICATIONS - AC

AC CHARACTERISTICS	Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ T_A ≤ +70°C for commercial -40°C ≤ T_A ≤ +85°C for industrial -40°C ≤ T_A ≤ +125°C for extended Operating voltage V_{DD} range as described in DC spec Section 13.1 and Section 13.2. LC parts operate for commercial/industrial temp's only.

FIGURE 13-4: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



R_L = 464Ω

C_L = 50 pF for all pins except OSC2/CLKOUT

15 pF for OSC2 output

13.4.3 TIMING DIAGRAMS AND SPECIFICATIONS

FIGURE 13-5: EXTERNAL CLOCK TIMING

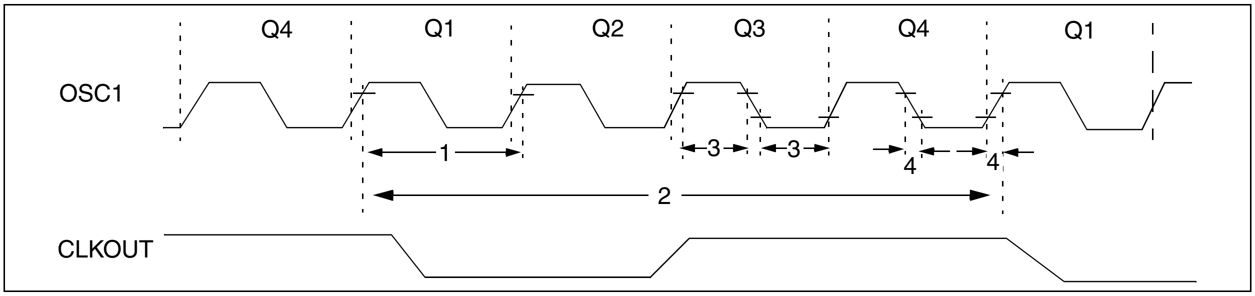


TABLE 13-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
1A	Fosc	External CLKIN Frequency (Note 1)	DC	—	4	MHz	RC and XT osc modes
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
1	Tosc	External CLKIN Period (Note 1)	250	—	—	ns	RC and XT osc modes
			250	—	—	ns	HS osc mode (-04)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			50	—	250	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
2	TCY	Instruction Cycle Time (Note 1)	200	—	DC	ns	TCY = 4/FOSC
3*	TosL, TosH	External Clock in (OSC1) High or Low Time	100	—	—	ns	XT oscillator
			2.5	—	—	μs	LP oscillator
			15	—	—	ns	HS oscillator
4*	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

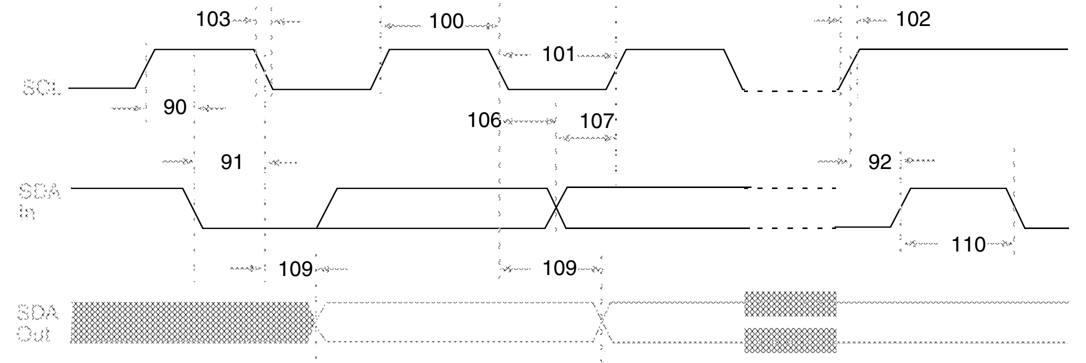
* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin.

When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

FIGURE 13-16: I^{2}C BUS DATA TIMING



Note: Refer to Figure 13-4 for load conditions.

TABLE 13-12: I^{2}C BUS DATA REQUIREMENTS

Param. No.	Sym	Characteristic		Min	Max	Units	Conditions
100*	THIGH	Clock high time	100 kHz mode	4.0	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
101*	TLOW	Clock low time	100 kHz mode	4.7	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	μs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
102*	TR	SDA and SCL rise time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
103*	TF	SDA and SCL fall time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
90*	TSU:STA	START condition setup time	100 kHz mode	4.7	—	μs	Only relevant for repeated START condition
			400 kHz mode	0.6	—	μs	
91*	THD:STA	START condition hold time	100 kHz mode	4.0	—	μs	After this period the first clock pulse is generated
			400 kHz mode	0.6	—	μs	
106*	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
107*	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	Note 2
			400 kHz mode	100	—	ns	
92*	TSU:STO	STOP condition setup time	100 kHz mode	4.7	—	μs	
			400 kHz mode	0.6	—	μs	
109*	TAA	Output valid from clock	100 kHz mode	—	3500	ns	Note 1
			400 kHz mode	—	—	ns	
110*	TBUF	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
	Cb	Bus capacitive loading		—	400	pF	

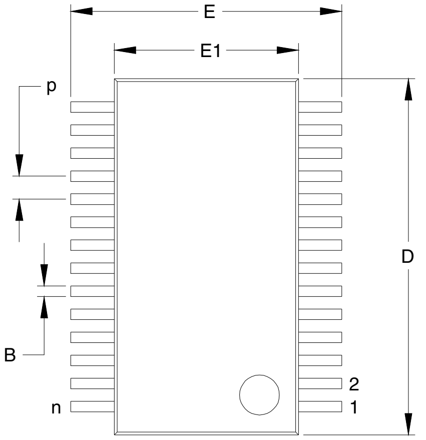
* These parameters are characterized but not tested.

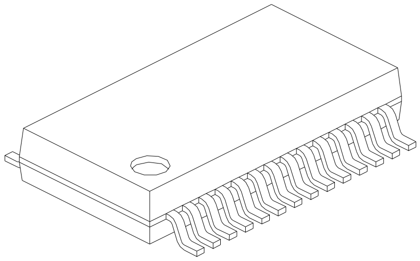
Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

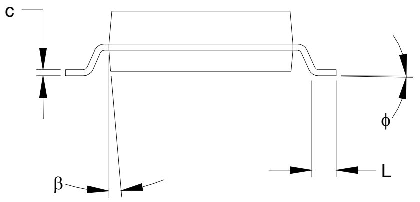
2: A fast-mode (400 kHz) I^{2}C-bus device can be used in a standard-mode (100 kHz) I^{2}C-bus system, but the requirement Tsu:DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max.+tsu;DAT = 1000 + 250 = 1250 ns (according to the standard-mode I^{2}C bus specification) before the SCL line is released.

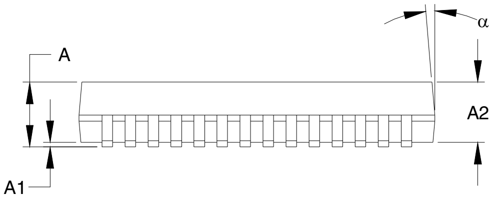
NOTES:

15.5 28-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)









Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.026			0.66	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.319	7.59	7.85	8.10
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.396	.402	.407	10.06	10.20	10.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	φ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.

JEDEC Equivalent: MS-150

Drawing No. C04-073